

# Impact of the Al Mole Fraction in the Bulk- and Surface-State Induced Instability of AlGaN/GaN HEMTs

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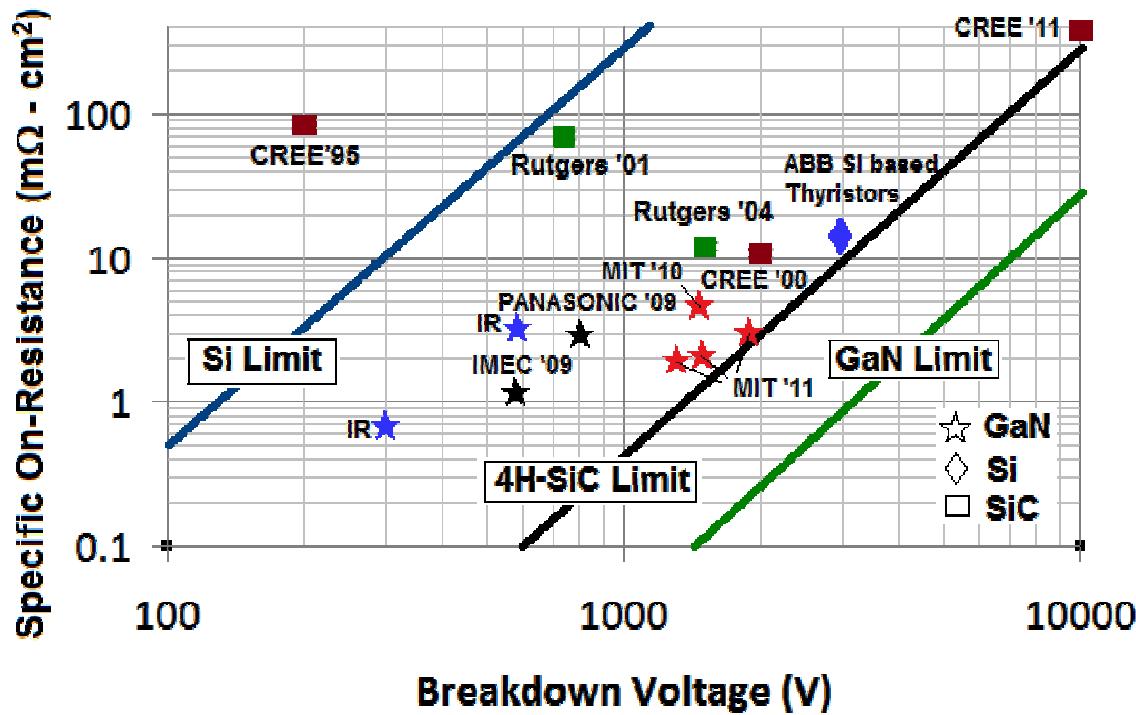
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Materials Research Society Spring Meeting,  
San Francisco, CA  
April 12, 2012



# GaN HEMTs for High Breakdown Voltage



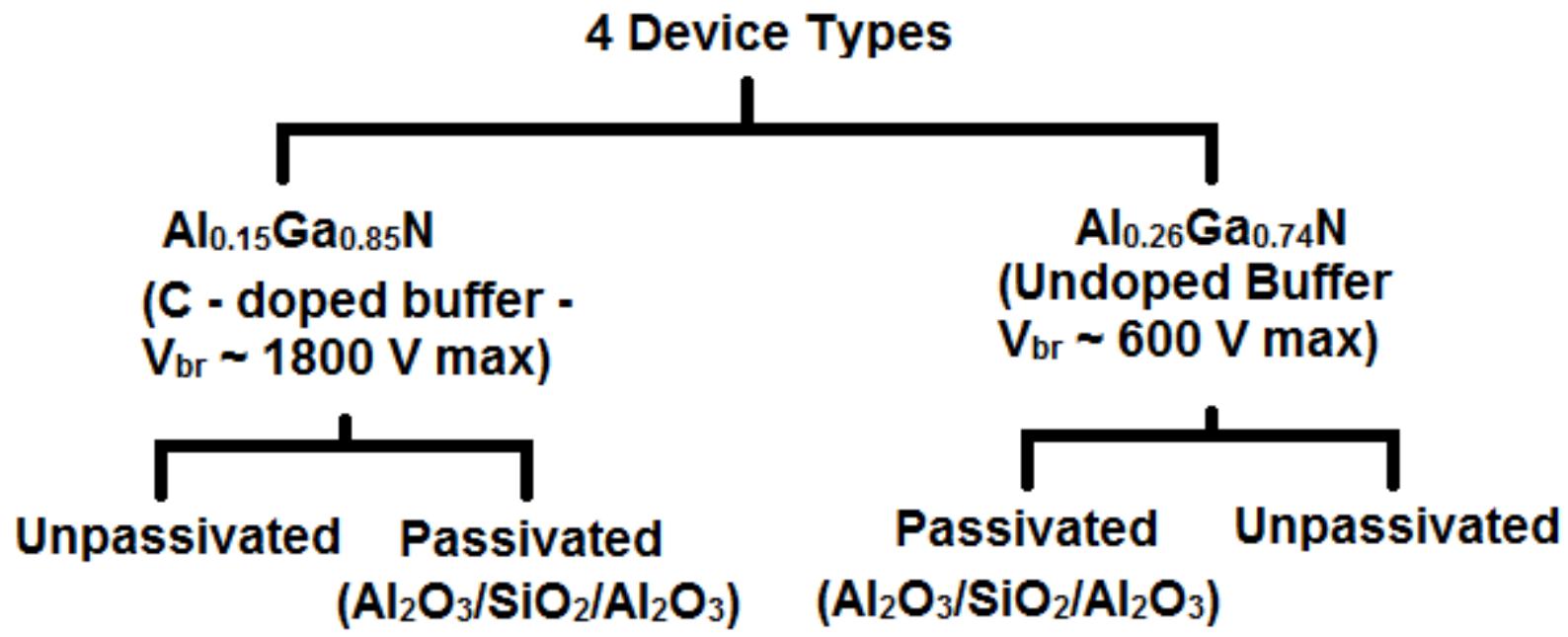
Wide bandgap GaN – theoretically has the highest breakdown voltage limit for given  $R_{on}$  (among Si, SiC, GaN)  
Greater commercial capability due to integration on Silicon.

Low Al percentage AlGaN required to reduce 2DEG density.  
Carbon doping employed in buffer to avoid punch-through.

Degradation mechanisms widely studied for RF HEMTs, with larger Al molefraction.  
**Low Al molefraction AlGaN has been studied comparatively less.**

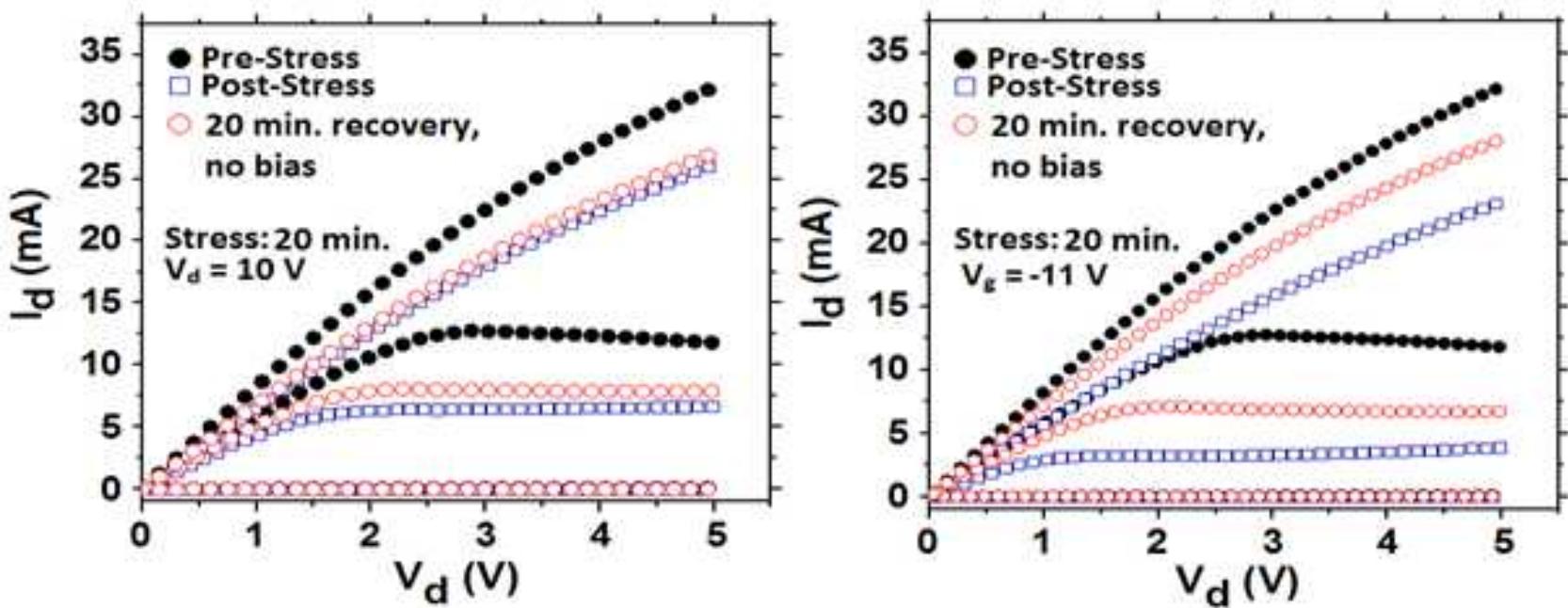


# The Devices



All devices grown on (111) Silicon

# Difference Between On-State and Off-State Stress



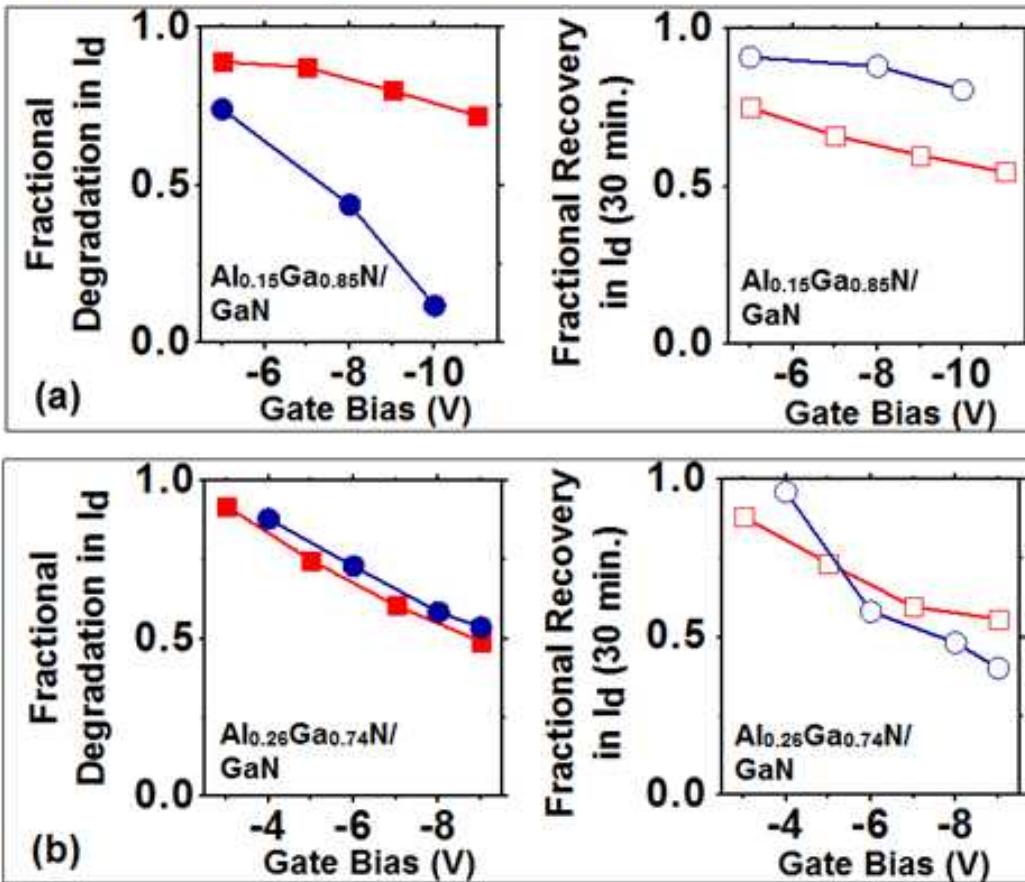
$$V_{ds} = 10V, V_{gs} = 0V$$

$$V_{ds} = 0V, V_{gs} = -11V$$

On-State drain bias produces much slower recovery than Off-State gate bias.

# Passivated vs Unpassivated – $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$ vs $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$

Passivated ■ Degradation □ Recovery  
Unpassivated ● Degradation ○ Recovery



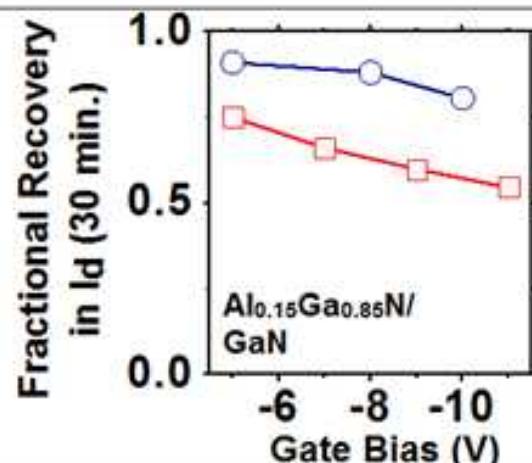
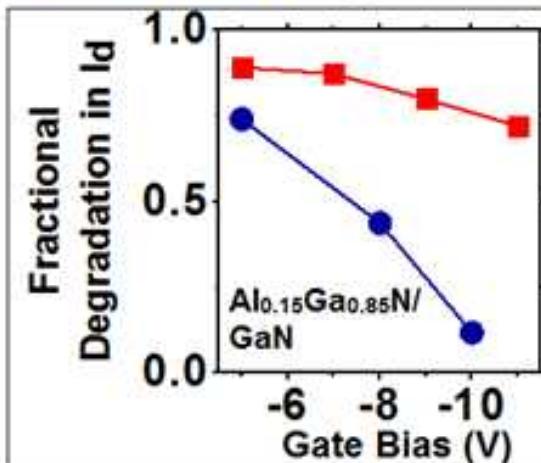
Fractional Recovery  
=  $(I_{d,\text{post-recovery}} - I_{d,\text{post-stress}})/(I_{d,\text{pre-stress}} - I_{d,\text{post-stress}})$  at  $V_{gs} = 1 \text{ V}$ ,  $V_{ds} = 5 \text{ V}$ .

Lack of passivation substantially increases trapping with fast recovery in  $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$  compared to  $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$

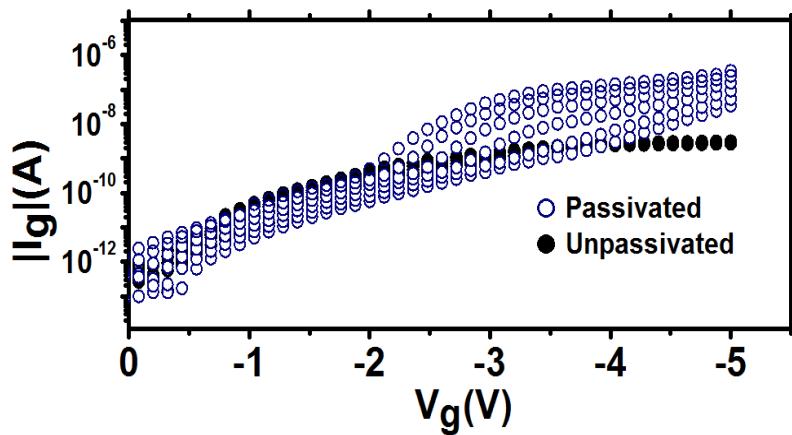
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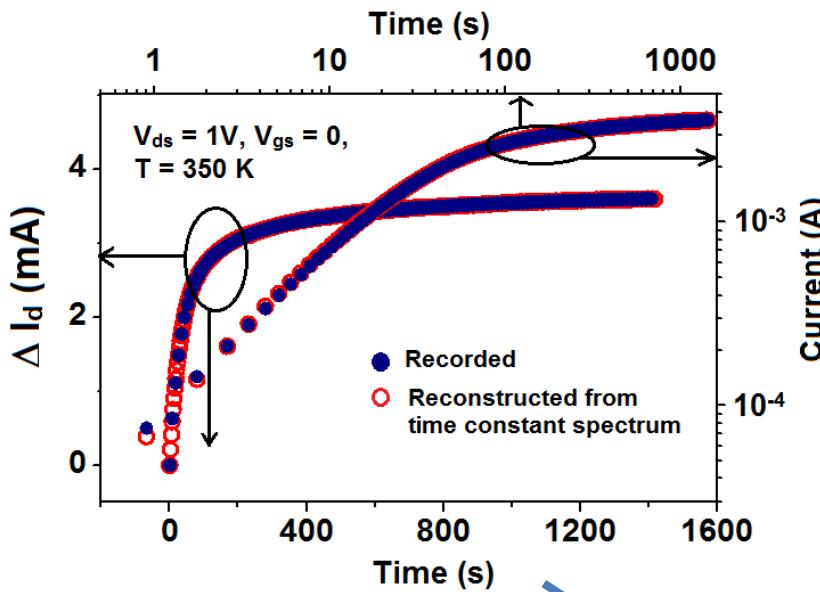


Passivation improves stability greatly, but gate leakage increases.



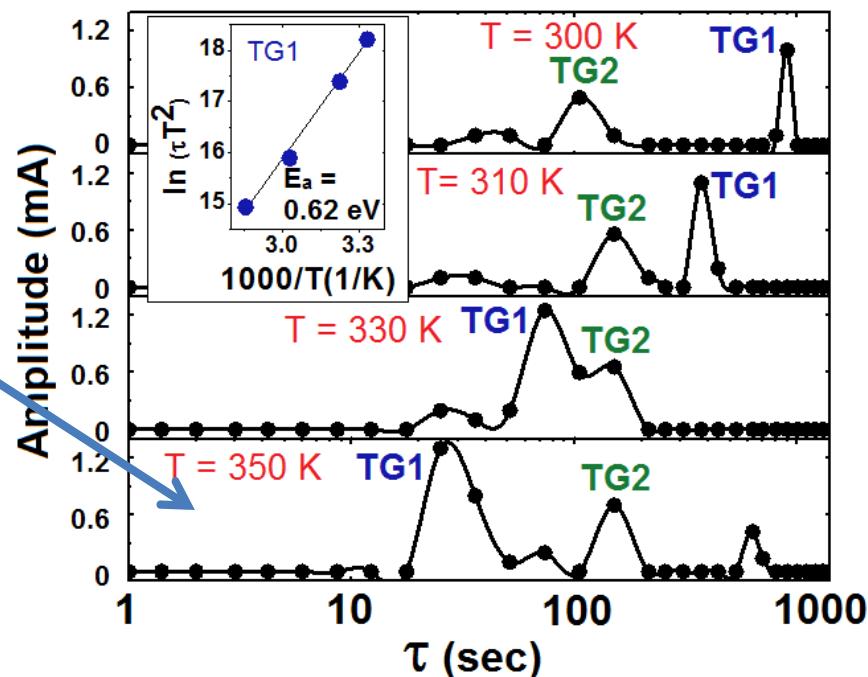
Large width power devices – require low gate leakage per unit length.  
Better gate dielectric need with Al<sub>0.15</sub>Ga<sub>0.85</sub>N.

# I-t based time constant spectra

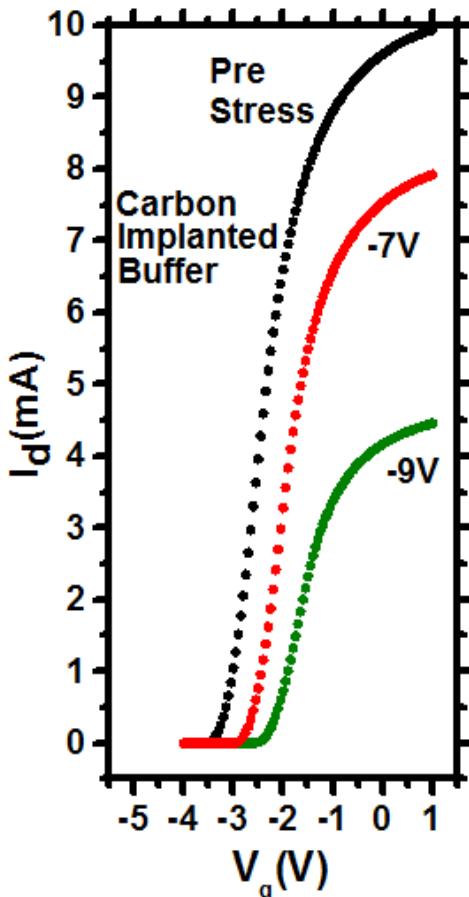
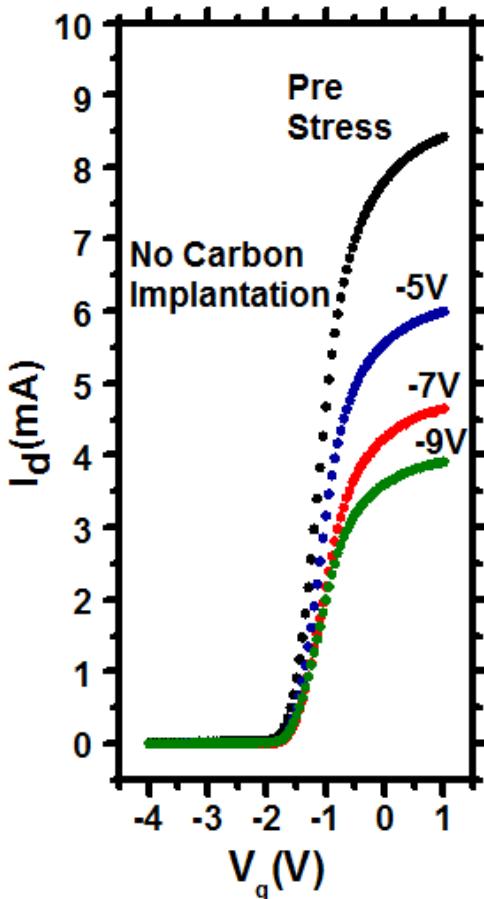


TG1 is temperature independent – most likely due to tunneling into 2DEG states

Two peaks – TG1 ( $E_a \sim 0.62$  eV) and TG2 are seen



# $V_{th}$ shifts and spatial location of TG1, TG2

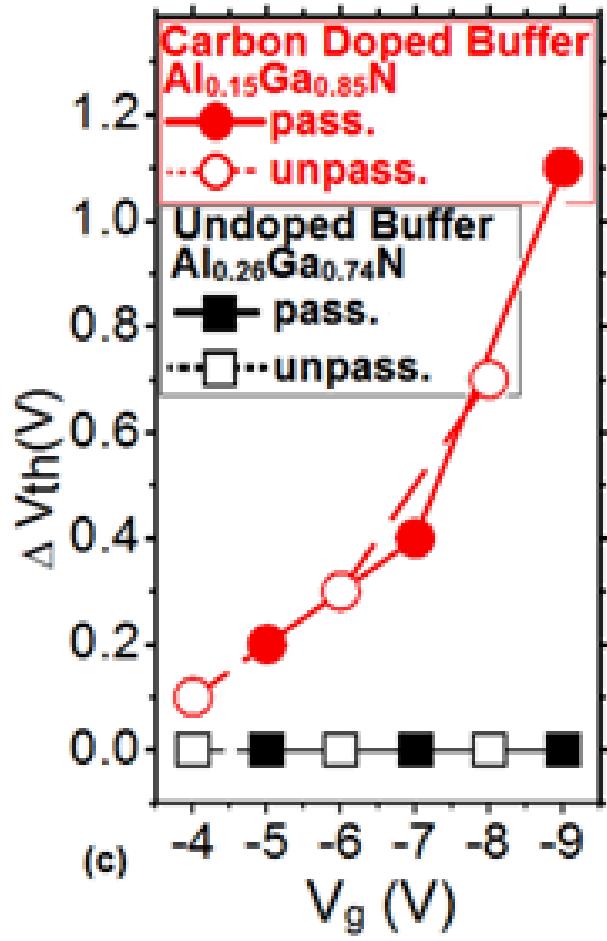


$\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$  devices (carbon doped) show  $V_{th}$  shifts, unlike the  $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$ . Even for more than 50 % current degradation – no  $V_{th}$  shift in non-carbon implanted devices.

AlGaN is depleted .  
Gate is fairly long (2 microns) – near gate trapping should not induce threshold shifts.

$V_{th}$  shift is most likely due trapping in carbon-doped buffer.

# $V_{th}$ shifts and spatial location of TG1, TG2



TG1, TG2 are seen in all devices.

$V_{th}$  shift in carbon doped samples – there are enough buffer carriers in off-state to induce  $V_{th}$  shifts.

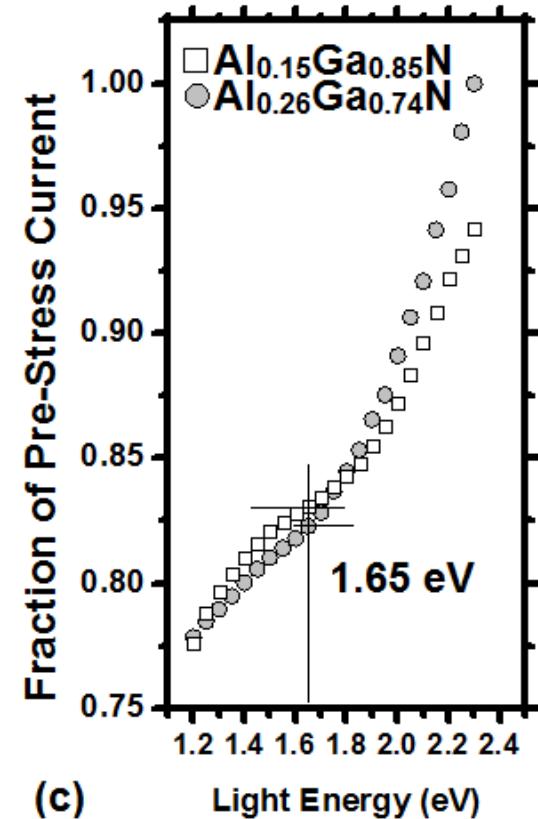
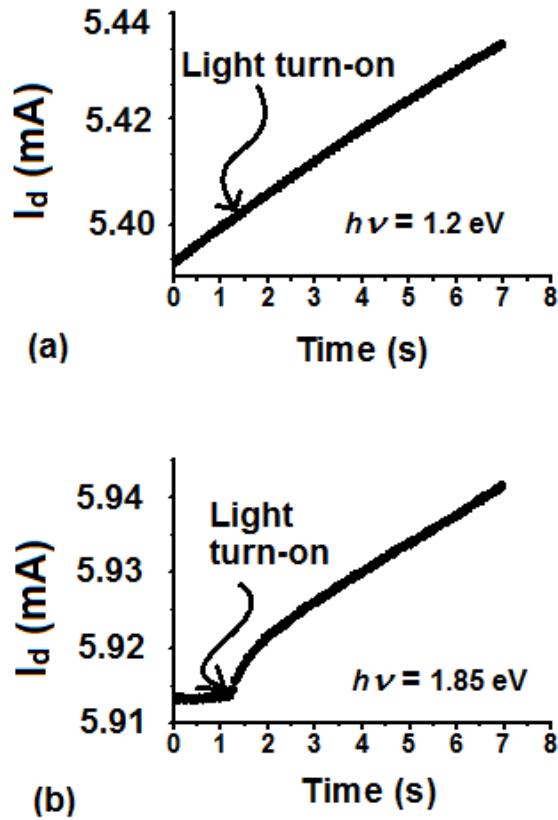
Should have induced slowly recoverable  $V_{th}$  shifts in all devices if they were buffer traps

Consistent with being AlGaN traps

# On-State Drain Bias and Optical Detrapping

Less than 50 % of the current due to on-state drain bias recovered thermally – so optical detrapping used.

Emission detected at ~ 1.65 eV.





# Conclusions

- Gate and Drain Stress produce trapping with different detrapping characteristics
- $\text{Al}_{0.15}\text{Ga}_{0.85}\text{N}$  shows much more vulnerability to gate stress in absence of passivation than  $\text{Al}_{0.26}\text{Ga}_{0.74}\text{N}$  in absence of passivation.
- Buffer Carbon doping introduces threshold voltage shifts.
- Two components TG1 ( $E_a = 0.62$  eV), TG2 (negligible temperature dependence observed in detrapping).
- Majority of drain bias induced degradation recovered at optical illumination with 1.65 eV and higher.